

Specialized Thermal Interface Material

Thermally Conductive Dispensable Jelly



MATERIAL

Gap filler jelly



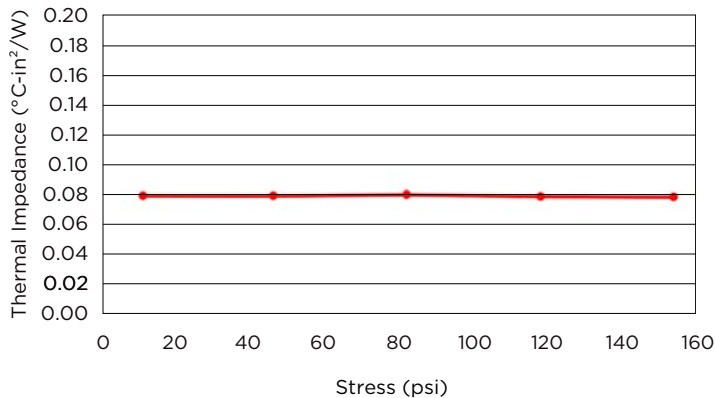
FEATURES

- Ideal for high-frequency RF applications
- Works well in vertical and high vibration environments
- Easily dispensable; fast-curing in room temperature
- Gel-like, less stress, easy rework
- Long-term reliability in harsh environments
- 5.7 W/m-K Thermal conductivity

Thermal Impedance Vs. Stress of T-CIP-57 (1 mm thick)

(@ 60°C: Step application of pressure
11, 46, 82, 118, 154 psi; ASTM D5470 modified)

— T-CIP-57



PROPERTIES	T-CIP-57
Composition	Gap filler jelly
Viscosity @ 25°C (Pa·s)	Part A: 5576 / Part B: 4168
Specific Gravity @ 25°C	Part A: 2.88 / Part B: 2.87
Mix Ratio (2-part)	1:1
Mixed Viscosity @ 25°C	4880 Pa·s
Tack-Free Time*	1 hr
Curing Conditions	4 hrs under 25 °C
Softness	65 Shore OO
Tensile Strength	0.23 MPa
Dielectric Breakdown Strength	9.6 kV/mm
Volume Resistance	3 TΩ·cm
Thermal Conductivity	5.7 W/m-K

* The time while the material is malleable.

GET IN TOUCH

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